

# BALANCED DUAL-LINE EMI FILTER

**OVERVIEW:** Multilayer chip EMI Filter has balanced impedance for superior filtering of radiated and conducted common-mode EMC noise. Terminal arrangement allows multiple connection options of this low ESL component for single-ended (power bypass) noise reduction applications.

**PART NUMBER: E13M0110B100MN**

<b>E13M</b>	<b>0110</b>	<b>B</b>	<b>100</b>	<b>M</b>	<b>N</b>
Size 0805 (2012)	SRF 110 MHz	TC +/- 15%	Voltage 100 VDC	Cap. Tol ±20%	Terminal Standard

## CHARACTERISTICS:

<b>Case Size</b>	0805 EIA (2012 Metric)
<b>SRF</b>	110MHz
<b>Inductance:</b>	56pH power bypass, 212pH dual-line EMI filter
<b>Capacitance:</b>	10nF (x 2)
<b>Rated Voltage:</b>	100 VDC
<b>Temperature Coefficient:</b>	±15% (-55 to +125°C)
<b>Dissipation Factor:</b>	≤ 2.5% (0.025)
<b>Insulation Resistance:</b>	IR> 500 Ω·F or 10GΩ whichever is less Measurement at 25°C, WVDC, time is 2 minutes max.
<b>Dielectric Strength:</b>	2.5XWVDC, 25°C, 50mA max.
<b>Capacitance Aging:</b>	≤ 2.5%/decade hour
<b>Test Conditions:</b>	1kHz±50Hz; 1.0±0.2VRMS

## PHYSICAL SIZE:

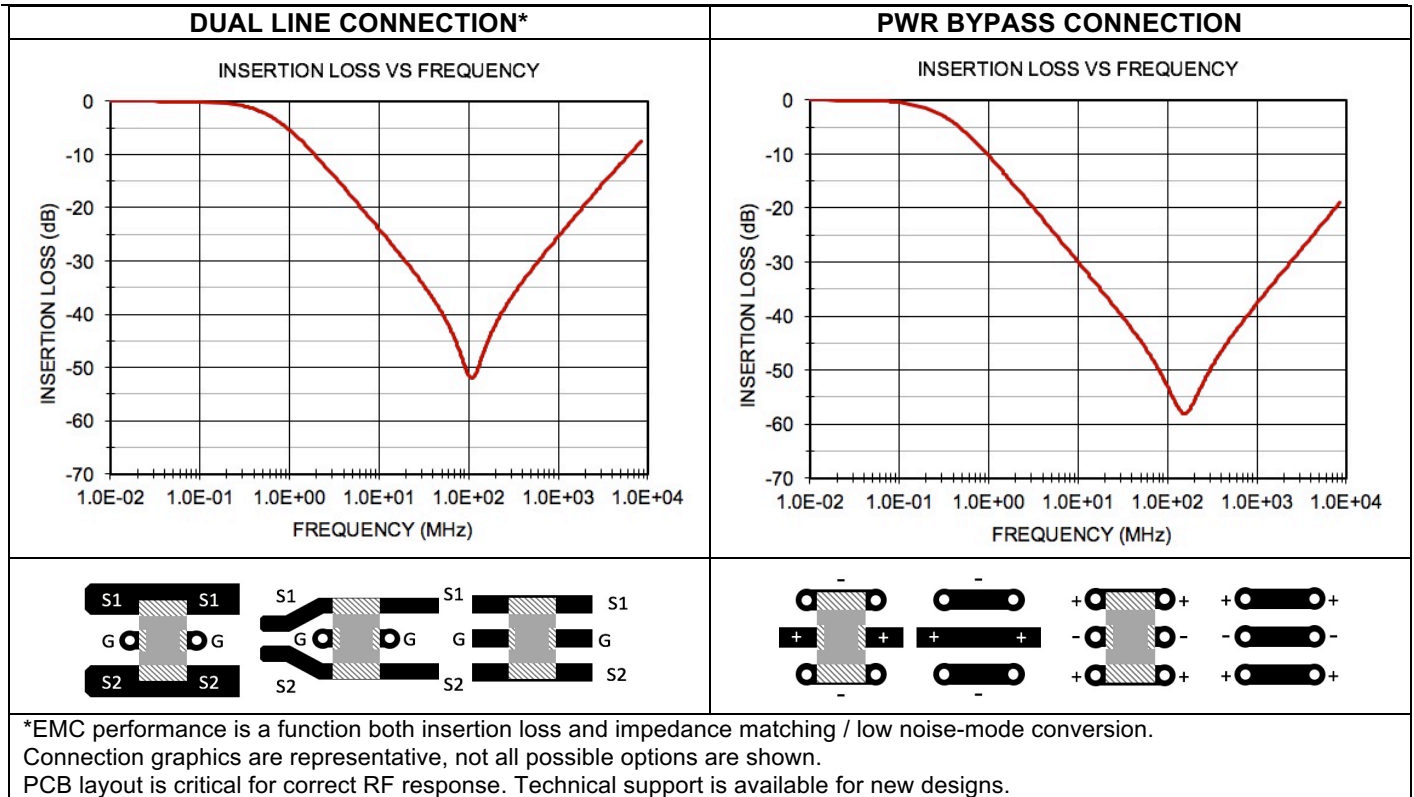
SIZE	IN	(mm)
<b>L</b>	.080 ± .008	2.032± .203
<b>W</b>	.050 ± .008	1.27 ± .203
<b>T</b>	.040 max.	1.016 max.
<b>EB</b>	.012 ± .008	.305 ± .203
<b>CB</b>	.022 ± .005	.559 ± .127
<b>WB</b>	.006 ± .004	.152 ± .100

## ENVIRONMENTAL

Meets Rohs & Reach directives	MSL Rating: 1
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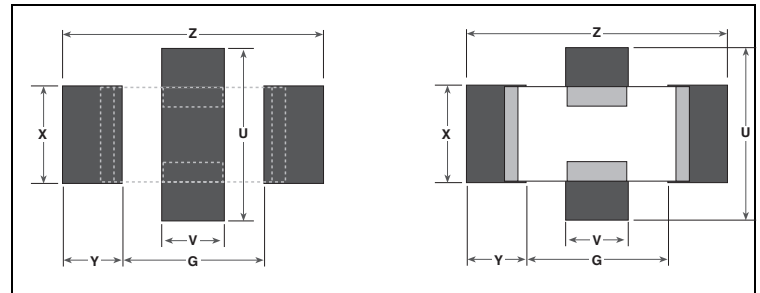
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## EMI FILTER INSERTION LOSS



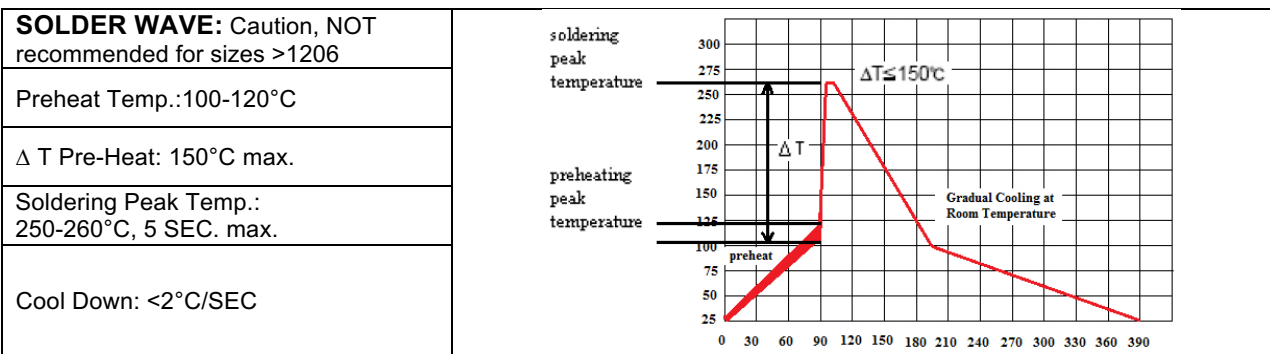
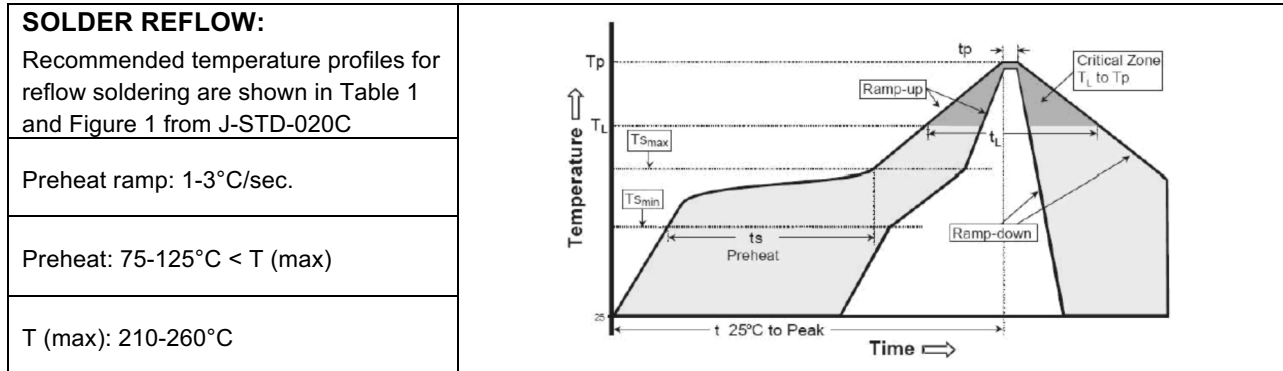
## SOLDER PAD RECOMMENDATIONS:

SOLDER REFLOW		
	IN	mm
<b>X</b>	0.050	1.270
<b>Y</b>	0.035	0.890
<b>G</b>	0.050	1.270
<b>V</b>	0.022	0.559
<b>U</b>	0.080	2.032
<b>Z</b>	0.120	3.050



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## SOLDER PROCESS RECOMMENDATIONS:



<b>SOLDERING IRON:</b> <b>NOT SUPPORTED</b> for use in mass production Not recommended for lab proto-typing, use solder reflow, hot-air tool, or conductive epoxy to avoid thermal damage and compromised test results. If Iron is used, follow below precautions:
<ul style="list-style-type: none"> <li>• Preheat circuit and capacitors to within 100° C of soldering temperature</li> <li>• No contact of iron tip with component</li> <li>• 20 watt iron output (max)</li> <li>• 350° C tip temperature (max)</li> <li>• 1.0 mm tip diameter (max)</li> <li>• Limit soldering time to 3 sec. (max)</li> </ul>

## PACKAGING SPECIFICATIONS

Specification EIA standard 481

PART SIZE	7" REEL QTY
0805 (2012)	4,000

## CONTACT INFORMATION

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